

Appl. No. 10/631,083
Amdt. dated June 23, 2005
Reply to Office action of Mar. 23, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1-9 (cancelled)

10. (original) A method for packaging an integrated circuit chip, said chip including active and passive surfaces with contact pads on said active surface, said method comprising the steps of:

providing a substrate, said substrate comprising:

a carrier tape;

a patterned metal layer having first and second surfaces and openings extending between said first and second surfaces, said second surface of said patterned metal layer removably attached to said carrier tape;

a first insulating layer covering said first surface of said patterned metal layer and portions of said carrier tape exposed in said openings in said patterned metal layer;

attaching said integrated circuit chip to said first insulating layer on said substrate;

encapsulating said chip; and

removing said carrier tape from said patterned metal layer to expose said second surface of said patterned metal layer.

11. (original) The method according to Claim 10, further comprising the step of:

applying a second insulating layer to said second surface of said patterned metal layer, said second insulating layer covering a portion of said second surface of said patterned metal layer and leaving said second surface of said patterned metal layer exposed in windows in said second insulating layer.

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12. (original) The method according to Claim 11, further comprising the step of:
attaching solder balls to said second surface of said patterned metal layer exposed in
said windows in said second insulating layer.
13. (cancelled)
14. (original) The method according to Claim 10, wherein said step of removing said carrier
tape is preceded by the step of exposing said carrier tape to ultra-violet radiation.
15. (original) The method according to Claim 11, wherein said step of applying a second
insulating layer comprises applying less than 30 μm of insulating layer to said second surface of
said patterned metal layer.
16. (original) The method according to Claim 11, wherein said step of applying a second
insulating layer comprises applying solder resist to said second surface of said patterned metal
layer.
17. (original) The method according to Claim 10, wherein said step of providing a substrate
with a first insulating layer comprises providing a substrate with a solder resist layer covering
said first surface of said patterned metal layer.